

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	3.6mΩ@10V	100A

Feature

- Split Gate Trench Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

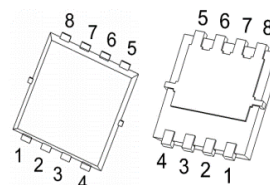
- Power Switching Application

MARKING:

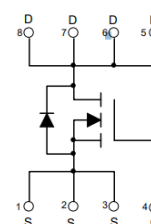


T036N04N = Device Code
 XX = Date Code
 Solid Dot = Green Indicator

PDFN3.3X3.3-8L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain - Source Voltage		V_{DS}	40	V
Gate - Source Voltage		V_{GS}	±20	V
Continuous Drain Current ¹	$T_C = 25^\circ\text{C}$	I_D	100	A
	$T_C = 100^\circ\text{C}$	I_D	65	A
Pulsed Drain Current ²		I_{DM}	400	A
Single Pulsed Avalanche Current ³		I_{AS}	32	A
Single Pulsed Avalanche Energy ³		E_{AS}	229	mJ
Power Dissipation ⁵	$T_C = 25^\circ\text{C}$	P_D	63	W
Thermal Resistance from Junction to Ambient ⁶		$R_{\theta JA}$	100	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case		$R_{\theta JC}$	1.98	$^\circ\text{C/W}$
Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~ +150	$^\circ\text{C}$

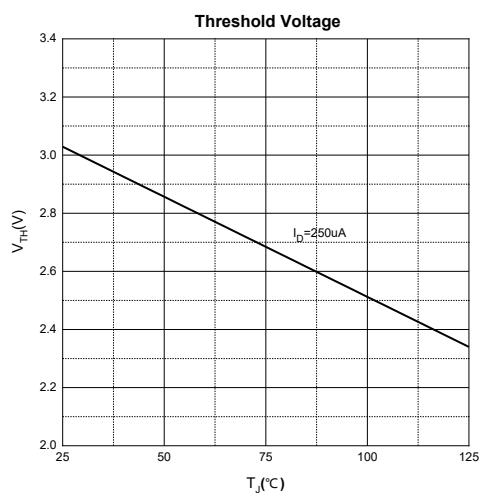
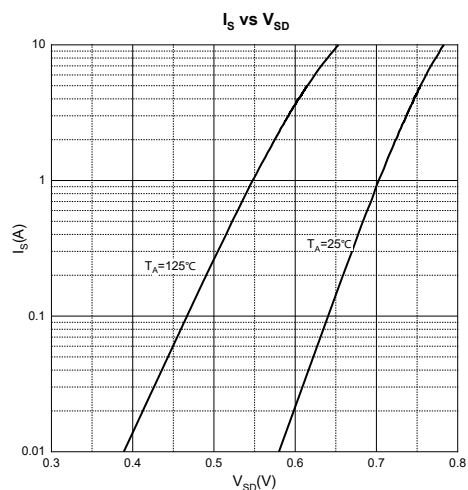
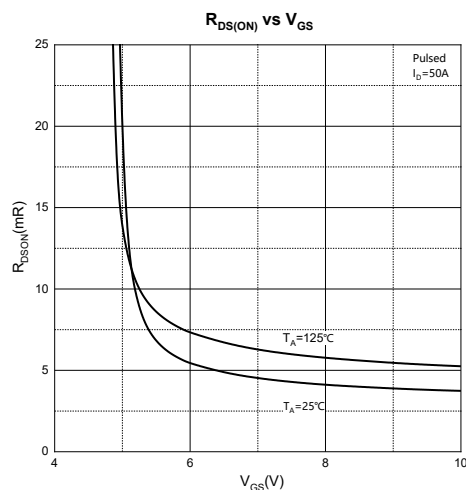
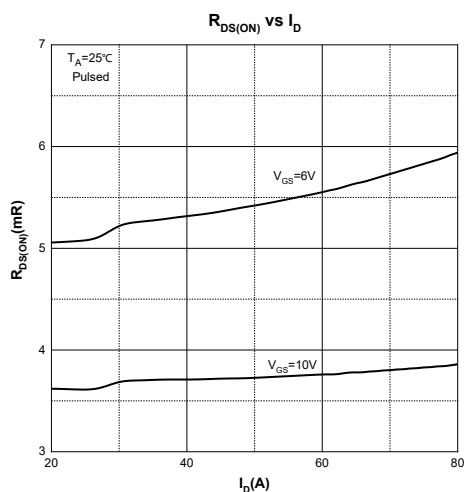
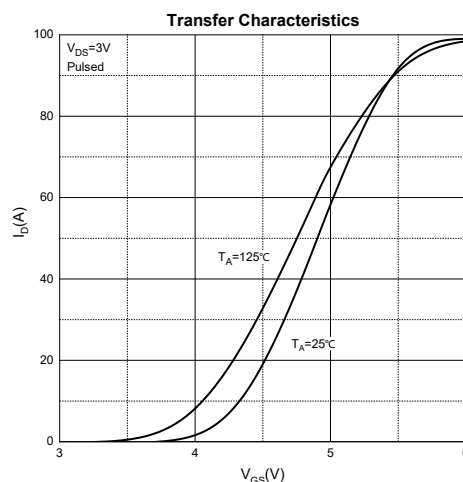
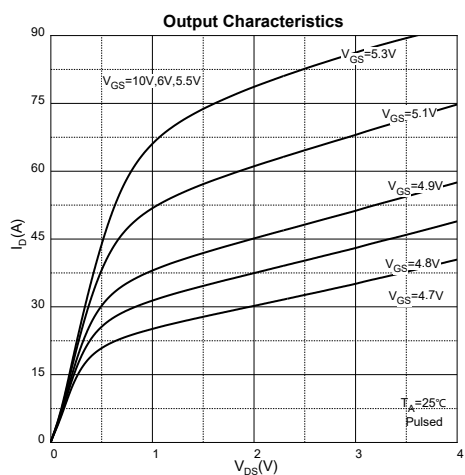
MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

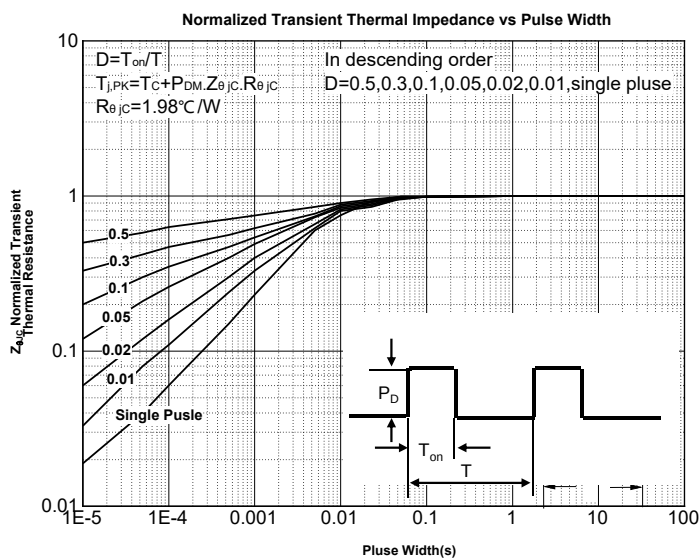
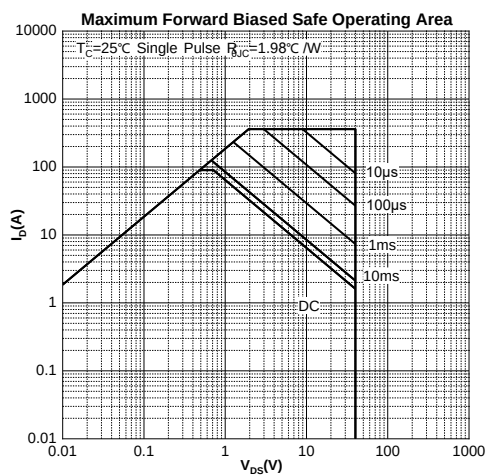
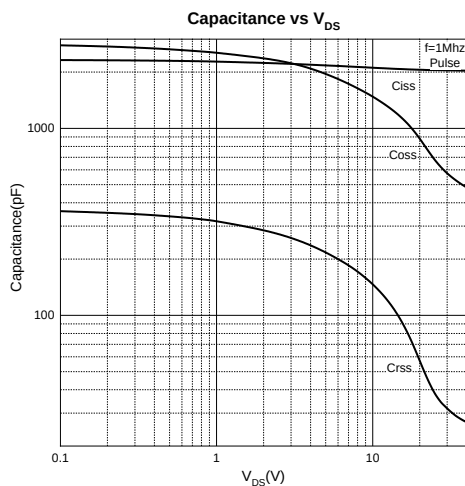
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2	3.1	4	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 10A		3.6	4.6	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 10V, I _D = 10A	10			S
Dynamic Characteristics						
Input Capacitance	C _{iSS}	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz		2026		pF
Output Capacitance	C _{oSS}			854		
Reverse Transfer Capacitance	C _{rSS}			34		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		4.3		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DD} = 20V, V _{GS} = 10V, I _D = 10A		27.6		nC
Gate-source Charge	Q _{gs}			8.7		
Gate-drain Charge	Q _{gd}			4.7		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 20V, V _{GS} = 10V, R _L = 1Ω R _G = 6Ω		12		ns
Turn-on Rise Time	t _r			63		
Turn-off Delay Time	t _{d(off)}			26		
Turn-off Fall Time	t _f			83		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = 10A			1.2	V

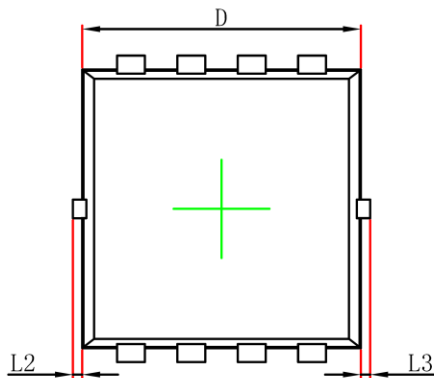
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.EAS condition: V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.
- 4.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 5.The power dissipation P_D is limited by T_{J(MAX)} = 150°C.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A = 25°C.

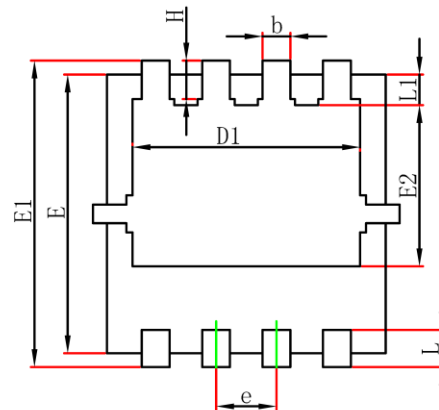
Typical Characteristics



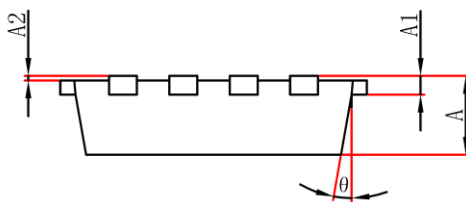


PDFN3.3X3.3-8L Package Information


Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	2.300	2.600	0.091	0.102
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°